IN THE SPECIFICATION

Please replace the paragraph beginning at page 12, line 19, with the following rewritten paragraph:

providing a mold for molding the anisotropically conductive film, the molding cavity of which is formed by a pair of ~~forces~~ faces,

Please replace the paragraph beginning at page 12, line 22, with the following rewritten paragraph:

forming, on a molding surface of one ~~force~~ face, a molding material layer obtained by incorporating a reinforcing material composed of insulating mesh or nonwoven fabric and conductive particles exhibiting magnetism into a liquid polymeric substance-forming material, which will become an elastic polymeric substance by curing, and forming, on a molding surface of the other ~~force~~ face, a molding material layer obtained by incorporating conductive particles into a liquid polymeric substance-forming material, which will become an elastic polymeric substance by curing, and

Please replace the paragraph beginning at page 13, line 5, with the following rewritten paragraph:

stacking the molding material layer formed on the molding surface of said one ~~force~~ face and the molding material layer formed on the molding surface of the other ~~force~~ face, thereafter applying a magnetic field having an intensity distribution to the thickness-wise directions of the respective molding material layers, and subjecting the molding material layers to a curing treatment, thereby forming the anisotropically conductive film.

Please replace the paragraph beginning at page 15, line 21, with the following rewritten paragraph:

According to the production process of the anisotropically conductive connector of the present invention, the molding material layer containing the reinforcing material, formed on the molding surface of one ~~force~~ face and the molding material layer formed on the molding surface of the other ~~force~~ face are stacked, and the respective molding material layers are subjected to a curing treatment in this state, so that an anisotropically conductive connector having a anisotropically conductive film containing the reinforcing material at only the surface layer portion on one surface side can be advantageously and surely produced.

Please replace the paragraph beginning at page 18, line 14, with the following rewritten paragraph:

FIG. 7 is a cross-sectional view illustrating a state that spacers and a supporting body have been arranged on the molding surface of a bottom ~~force~~ face.

Please replace the following paragraph at page 18, between lines 16 and 17:

FIG. 8 is a cross-sectional view illustrating a state that a reinforcing material has been arranged on the molding surface of the top ~~force~~ face.

Please replace the paragraph beginning at page 18, line 17, with the following rewritten paragraph:

FIG. 9 is a cross-sectional view illustrating a state that a first molding material layer has been formed on the molding surface of a top ~~force~~ face, and a second molding material layer has been formed on the molding surface of the bottom ~~force~~ face.

Please replace the paragraph beginning at page 21, line 27, with the following rewritten paragraph:

50 Top ~~force~~ face,

Please replace the paragraph beginning at page 22, line 6, with the following rewritten paragraph:

55 Bottom ~~force~~ face,

Please replace the paragraph beginning at page 37, line 25, with the following rewritten paragraph:

FIG. 6 is a cross-sectional view illustrating the construction of an exemplary mold used for producing the anisotropically conductive connector according to the present invention. This mold is so constructed that a top ~~force~~ face 50 and a bottom ~~force~~ face 55 making a pair therewith are arranged so as to be opposed to each other. A molding cavity 59 is defined between a molding surface (lower surface in FIG. 6) of the top ~~force~~ face 50 and a molding surface (upper surface in FIG. 6) of the bottom ~~force~~ face 55.

Please replace the paragraph beginning at page 38, line 7, with the following rewritten paragraph:

In the top ~~force~~ face 50, ferromagnetic substance layers 52 are formed in accordance with an arrangement pattern corresponding to a pattern of conductive path-forming parts 11 in the intended anisotropically conductive connector 10 on a surface (lower surface in FIG. 6) of a ferromagnetic substance substrate 51, and non-magnetic substance layers 53 composed of portions 53b (hereinafter referred to as "portions 53b" merely) having substantially the same thickness as the thickness of the ferromagnetic substance layers 52 and portions 53a

(hereinafter referred to as "portions 53a" merely) having a thickness greater than the thickness of the ferromagnetic substance layers 52 are formed at other places than the ferromagnetic substance layers 52. A difference in level is defined between the portion 53a and the portion 53b in the non-magnetic substance layers 53, thereby forming a recess 60 in the surface of the top ~~force~~ face 50.

Please replace the paragraph beginning at page 38, line 24, with the following rewritten paragraph:

In the bottom ~~force~~ face 55 on the other hand, ferromagnetic substance layers 57 are formed in accordance with a pattern corresponding to the pattern of the conductive path-forming parts 11 in the intended anisotropically conductive connector 10 on a surface (upper surface in FIG. 6) of the ferromagnetic substance substrate 56, and non-magnetic substance layers 58 having a thickness greater than the thickness of the ferromagnetic substance layers 57 are formed at other places than the ferromagnetic substance layers 57. A difference in level is defined between the non-magnetic substance layer 58 and the ferromagnetic substance layer 57, whereby recessed portions 57a for forming projected portions 11a in the anisotropically conductive film 10A are formed in the molding surface of the bottom ~~force~~ face 55.

Please replace the paragraph beginning at page 39, line 12, with the following rewritten paragraph:

As a material for forming the respective ferromagnetic substance substrates 51, 56 in the top ~~force~~ face 50 and bottom ~~force~~ face 55, may be used a ferromagnetic metal such as iron, iron-nickel alloy, iron-cobalt alloy, nickel or cobalt. The ferromagnetic substance substrates 51, 56 preferably have a thickness of 0.1 to 50 mm, and surfaces thereof are

preferably smooth and subjected to a chemical degreasing treatment and/or mechanical polishing treatment.

Please replace the paragraph beginning at page 39, line 20, with the following rewritten paragraph:

As a material for forming the respective ferromagnetic substance layers 52, 57 in the top ~~force~~ face 50 and bottom ~~force~~ face 55, may be used a ferromagnetic metal such as iron, iron-nickel alloy, iron-cobalt alloy, nickel or cobalt. The ferromagnetic substance layers 52, 57 preferably have a thickness of at least 10 μm. If this thickness is smaller than 10 μm, it is difficult to apply a magnetic field having sufficient intensity distribution to the molding material layers formed in the mold. As a result, it is difficult to gather the conductive particles at a high density at portions to become conductive path-forming parts 11 in the molding material layers, and so a good anisotropically conductive connector may not be provided in some cases.

Please replace the paragraph beginning at page 40, line 7, with the following rewritten paragraph:

As a material for forming the respective non-magnetic substance layers 53, 58 in the top ~~force~~ face 50 and bottom ~~force~~ face 55, may be used a non-magnetic metal such as copper, a polymeric substance having heat resistance, or the like. However, a polymeric substance cured by radiation may preferably be used in that the non-magnetic substance layers 53, 58 can be easily formed by a technique of photolithography. As a material thereof, may be used, for example, a photoresist such as an acrylic type dry film resist, epoxy type liquid resist or polyimide type liquid resist.

Please replace the paragraph beginning at page 40, line 18, with the following rewritten paragraph:

The thickness of the non-magnetic substance layers 58 in the bottom ~~force~~ face 55 is preset according to the projected height of the projected portions 11a to be formed and the thickness of the ferromagnetic substance layers 57.

Please replace the paragraph beginning at page 40, line 25, with the following rewritten paragraph:

As illustrated in FIGS. 4 and 5, a supporting body 71 having an opening 73 and positioning holes 72 is first provided, and the supporting body 71 is fixed and arranged at a prescribed position of the bottom ~~force~~ face 55 through the frame-like spacer 54b having an opening at a central position, as illustrated in FIG. 7. Further, the frame-like spacer 54a having an opening at a central position is arranged on the supporting body 71.

Please replace the paragraph beginning at page 41, line 17, with the following rewritten paragraph:

As illustrated in FIG. 8, a sheet-like reinforcing material H formed of insulating mesh or nonwoven fabric is then arranged in the recess 60 (see FIG. 6) in the molding surface of the top ~~force~~ face 50, and the first molding material is further charged into the recess 60, thereby forming a first molding material layer 61a with the conductive particles exhibiting magnetism, non-magnetic insulating particles and reinforcing material contained in the polymeric substance-forming material as illustrated in FIG. 9. On the other hand, the second molding material is charged into a cavity defined by the bottom ~~force~~ face 55, the spacers 54a and 54b, and the supporting body 71, thereby forming a second molding material layer 61b

with the conductive particles exhibiting magnetism contained in the polymeric substance-forming material.

Please replace the paragraph beginning at page 42, line 5, with the following rewritten paragraph:

As illustrated in FIG. 10, the top ~~force~~ face 50 is arranged in alignment on the spacer 54a, whereby the first molding material layer 61a is stacked on the second molding material layer 61b.

Please replace the paragraph beginning at page 42, line 9, with the following rewritten paragraph:

Electromagnets (not illustrated) respectively arranged on an upper surface of the ferromagnetic substance substrate 51 in the top ~~force~~ face 50 and a lower surface of the ferromagnetic substance substrate 56 in the bottom ~~force~~ face 55 are then operated, whereby a parallel magnetic field having a intensity distribution, i.e., a parallel magnetic field having higher intensity at portions between the ferromagnetic substance layers 52 of the top ~~force~~ face 50 and their corresponding ferromagnetic substance layers 57 of the bottom ~~force~~ face 55, is applied to the thickness-wise directions of the first molding material layer 61a and the second molding material layer 61b. As a result, in the first molding material layer 61a and the second molding material layer 61b, the conductive particles dispersed in the respective molding material layers are gathered at portions to become the conductive path-forming parts 11 located between each of the ferromagnetic substance layers 52 of the top ~~force~~ face 50 and their corresponding ferromagnetic substance layers 57 of the bottom ~~force~~ face 55, and oriented so as to align in the thickness-wise directions of the respective molding material layers.

Please replace the paragraph beginning at page 44, line 16, with the following rewritten paragraph:

According to such a production process, the first molding material layer 61a containing the reinforcing material and formed on the molding surface of the top ~~force~~ face 50 is stacked on the second molding material layer 61b formed on the molding surface of the bottom ~~force~~ face 55, and the respective molding material layers are subjected to a curing treatment in this state, so that an anisotropically conductive connector 10 having an anisotropically conductive film 10A with the reinforcing material contained in only the surface layer portion 10B on one surface side can be advantageously and surely produced.

Please replace the paragraph beginning at page 58, line 26, with the following rewritten paragraph:

Ferromagnetic substance substrates (51, 56) of both top ~~force~~ face (50) and bottom ~~force~~ face (55) are such that their materials are iron, and the thickness is 6 mm.

Please replace the paragraph beginning at page 59, line 2, with the following rewritten paragraph:

Ferromagnetic substance layers (52, 57) of both top ~~force~~ face (50) and bottom ~~force~~ face (55) are such that their materials are nickel, the diameter is 0.45 mm (circular), the thickness is 0.1 mm, the arrangement pitch (center distance) is 0.8 mm, and the number of the ferromagnetic substance layers in each ~~force~~ face is 288 (12 × 24).

Please replace the paragraph beginning at page 59, line 8, with the following rewritten paragraph:

Non-magnetic substance layers (53, 58) of both top ~~force~~ face (50) and bottom ~~force~~ face (55) are such that their materials are dry film resists subjected to a curing treatment, the thickness of portions (53a) in the non-magnetic substance layers (53) of the top ~~force~~ face (50) is 0.3 mm, the thickness of portions (53b) is 0.1 mm, and the thickness of the non-magnetic substance layers (58) of the bottom ~~force~~ face (55) is 0.15 mm.

Please replace the paragraph beginning at page 60, line 14, with the following rewritten paragraph:

On the other hand, a spacer (54b) having a thickness of 0.1 mm and a rectangular opening of 20 mm by 13 mm in dimensions was arranged in alignment on a molding surface of the bottom ~~force~~ face (55) of the mold, the above-described supporting support (71) was arranged in alignment on this spacer (54b), a spacer (54a) having a thickness of 0.1 mm and a rectangular opening of 20 mm by 13 mm in dimensions was further arranged in alignment on this supporting body (71), and the molding material prepared was applied by screen printing, thereby forming a second molding material layer (61b), in which the conductive particles were contained in the liquid addition type silicone rubber, and the thickness of portions located on the non-magnetic substance layers (58) was 0.3 mm, in a cavity defined by the bottom ~~force~~ face (55), spacers (54a, 54b) and supporting body (71).

Please replace the paragraph beginning at page 61, line 3, with the following rewritten paragraph:

The first molding material layer (61a) formed on the top ~~force~~ face (50) and the second molding material layer (61b) formed on the bottom ~~force~~ face (55) were stacked on each other in alignment.

Please replace the paragraph beginning at page 61, line 7, with the following rewritten paragraph:

The respective molding material layers formed between the top ~~force~~ face (50) and the bottom ~~force~~ face (55) were subjected to a curing treatment under conditions of 100°C for 1 hour while applying a magnetic field of 2 T to portions located between the ferromagnetic substance layers (52, 57) in the thickness-wise direction by electromagnets, thereby forming an anisotropically conductive film (10A).

Please replace the paragraph beginning at page 62, line 5, with the following rewritten paragraph:

An anisotropically conductive connector was produced in the same manner as in Example 1 except that the reinforcing material was not arranged on the molding surface of the top ~~force~~ face (50). The anisotropically conductive film (10A) in the resultant anisotropically conductive connector (10) is in a form of a rectangle having dimensions of 20 mm by 13 mm, wherein the thickness of conductive path-forming parts (11) is 0.55 mm, the thickness of insulating parts (15) is 0.5 mm, the number of conductive path-forming parts (11) is 288 (12 × 24), the diameter of each conductive path-forming part (11) is 0.45 mm, and the arrangement pitch (center distance) of the conductive path-forming parts (11) is 0.8 mm.

Please replace the paragraph beginning at page 68, line 14, with the following rewritten paragraph:

A supporting body of the following specification was produced in accordance with the construction shown in FIG. 4, and a mold of the following specification for molding an anisotropically conductive film was produced in accordance with the construction shown in FIG. 6 except that non-magnetic substance layers of a top ~~force~~ face had an even thickness, and no recess was formed in the surface of the top ~~force~~ face.

Please replace the paragraph beginning at page 69, line 6, with the following rewritten paragraph:

Ferromagnetic substance substrates (51, 56) of both top ~~force~~ face (50) and bottom ~~force~~ face (55) are such that their materials are iron, and the thickness is 6 mm.

Please replace the paragraph beginning at page 69, line 9, with the following rewritten paragraph:

Ferromagnetic substance layers (52, 57) of both top ~~force~~ face (50) and bottom ~~force~~ face (55) are such that their materials are nickel, the diameter is 0.45 mm (circular), the thickness is 0.1 mm, the arrangement pitch (center distance) is 0.8 mm, and the number of the ferromagnetic substance layers in each ~~force~~ face is 288 (12 × 24).

Please replace the paragraph beginning at page 69, line 15, with the following rewritten paragraph:

Non-magnetic substance layers (53, 58) of both top ~~force~~ face (50) and bottom ~~force~~ face (55) are such that their materials are dry film resists subjected to a curing treatment, the thickness of the non-magnetic substance layers (53) of the top ~~force~~ face (50) is 0.1 mm, and

the thickness of the non-magnetic substance layers (58) of the bottom ~~force~~ face (55) is 0.15 mm.

Please replace the paragraph beginning at page 70, line 10, with the following rewritten paragraph:

A spacer (54a) having a thickness of 0.2 mm, in which a rectangular opening of 20 mm by 13 mm in dimensions had been formed, was arranged in alignment on a molding surface of the top ~~force~~ face (50) of the above-described mold, a sheet-like reinforcing material composed of mesh (thickness: 0.115 mm, opening diameter: 184 μm, opening rate: 52%) formed by polyarylate type composite fiber (fiber diameter: 70 μm) was arranged within the opening of the spacer (54a), and the molding material prepared was further applied by screen printing, thereby forming a first molding material layer (61a) having a thickness of 0.2 mm with the conductive particles and reinforcing material contained in the liquid addition type silicone rubber.

Please replace the paragraph beginning at page 70, line 23, with the following rewritten paragraph:

On the other hand, a spacer (54b) having a thickness of 0.15 mm, in which a rectangular opening of 20 mm by 13 mm in dimensions had been formed, was arranged in alignment on a molding surface of the bottom ~~force~~ face (55) of the mold, the above-described supporting body (71) was arranged in alignment on this spacer (54b), and the molding material prepared was applied by screen printing, thereby forming a second molding material layer (61b), in which the conductive particles were contained in the liquid addition type silicone rubber, and the thickness of portions located on the non-magnetic substance

layers (58) was 0.3 mm, in a cavity defined by the bottom ~~force~~ face (55), spacer (54b) and supporting body (71).

Please replace the paragraph beginning at page 71, line 9, with the following rewritten paragraph:

The first molding material layer (61a) formed on the top ~~force~~ face (50) and the second molding material layer (61b) formed on the bottom ~~force~~ face (55) were stacked on each other in alignment.

Please replace the paragraph beginning at page 71, line 13, with the following rewritten paragraph:

The respective molding material layers formed between the top ~~force~~ face (50) and the bottom ~~force~~ face (55) were subjected to a curing treatment under conditions of 100°C for 1 hour while applying a magnetic field of 2 T to portions located between the ferromagnetic substance layers (52, 57) in the thickness-wise direction by electromagnets, thereby forming an anisotropically conductive film (10A).

Please replace the paragraph beginning at page 72, line 12, with the following rewritten paragraph:

An anisotropically conductive connector (10) according to the present invention was produced in the same manner as in Example 2 except that the spacer (54a) arranged on the molding surface of the top ~~force~~ face (50) was changed to that having a thickness of 0.1 mm, and the spacer (54b) arranged on the molding surface of the bottom ~~force~~ face (55) was changed to that having a thickness of 0.1 mm. The anisotropically conductive film (10A) in the resultant anisotropically conductive connector (10) is in a form of a rectangle having

dimensions of 20 mm by 13 mm, wherein the thickness of conductive path-forming parts (11) is 0.40 mm, the thickness of insulating parts (15) is 0.35 mm, the number of conductive path-forming parts (11) is 288 (12 × 24), the diameter of each conductive path-forming part (11) is 0.45 mm, and the arrangement pitch (center distance) of the conductive path-forming parts (11) is 0.8 mm. Further, a ratio r1/r2 of the opening diameter of the mesh to the average particle diameter of the conductive particles is 6.13.

Please replace the paragraph beginning at page 74, line 4, with the following rewritten paragraph:

An anisotropically conductive connector was produced in the same manner as in Example 2 except that the reinforcing material was not arranged on the molding surface of the top ~~force~~ face (50). The anisotropically conductive film in the resultant anisotropically conductive connector is in a form of a rectangle having dimensions of 20 mm by 13 mm, wherein the thickness of conductive path-forming parts is 0.55 mm, the thickness of insulating parts is 0.50 mm, the number of conductive path-forming parts is 288 (12 × 24), the diameter of each conductive path-forming part is 0.45 mm, and the arrangement pitch (center distance) of the conductive path-forming parts is 0.8 mm.

Please replace the paragraph beginning at page 74, line 20, with the following rewritten paragraph:

An anisotropically conductive connector was produced in the same manner as in Example 3 except that the reinforcing material was not arranged on the molding surface of the top ~~force~~ face (50). The anisotropically conductive film in the resultant anisotropically conductive connector is in a form of a rectangle having dimensions of 20 mm by 13 mm, wherein the thickness of conductive path-forming parts is 0.40 mm, the thickness of

insulating parts is 0.35 mm, the number of conductive path-forming parts is 288 (12 × 24), the diameter of each conductive path-forming part is 0.45 mm, and the arrangement pitch (center distance) of the conductive path-forming parts is 0.8 mm.